

Dry Etching Agent for Semiconductors PFC-116(C2F6)

TECHNICAL
DATASHEET

The dry etching agent PFC-116(C2F6) is a high purity etching gas for use in semiconductor manufacturing.

Introduction

- Purity is 99.999vol% (5N) or more for semiconductor manufacturing.
- Suitable for cleaning applications mainly in the semiconductor manufacturing process.

General physical properties

Items	Unit	Numeric Value
Molecular formula	-	C2F6
Molecular weight	-	138.01
Boiling point	°C	-78.2
Vapor pressure(19.65°C)	MPa	2.981

Inspection Items

- Purity (excluding air content), other fluorocarbons, acid content, moisture, air content

Please contact us for details on the quality levels of individual items.

Handling method/Safety information

- Be sure to read the notes on SDS and labels before use.
- This product has been developed for industrial purposes and we shall not guarantee the safety if used for any other purposes. If it is going to be used for medical or food applications, please contact us in advance.

Packing specification

- 10L container, 47L container, etc.

For more information, visit our website.

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